

# BRES24V0M2B3MAQ

Rev.B Apr.-2024



DATA SHEET

SOT-23 TVS

TVS Array in a SOT23 Plastic Package.

1ns

30KV

Q

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## / Absolute Maximum Ratings(Ta=25 )

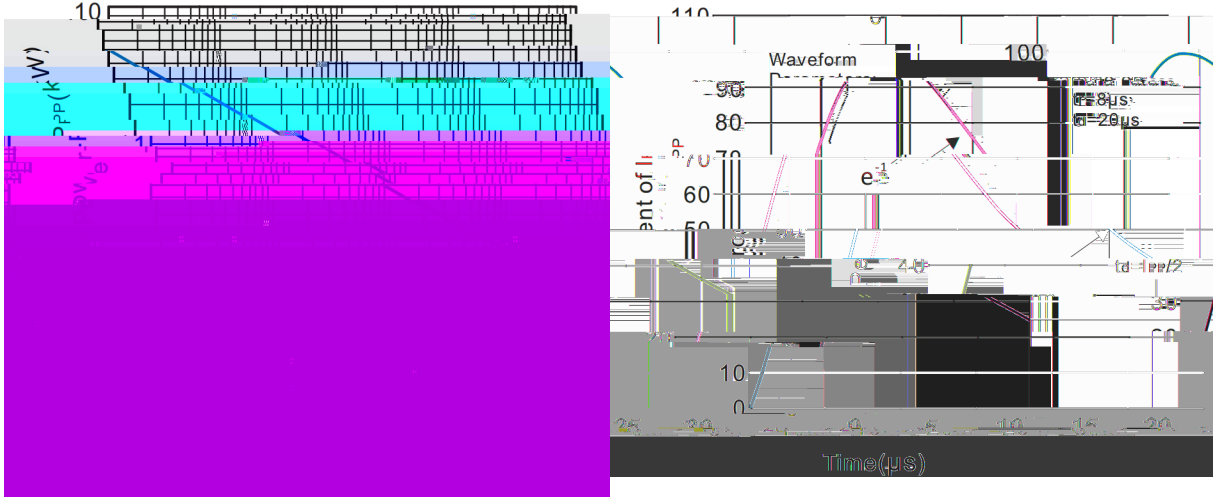
Parameter	Symbol	Rating	Unit
Peak Pulse Power (tp = 8/20 s)	P <sub>PP</sub>	350	W
Peak Pulse Current (tp = 8/20 s)	I <sub>PP</sub>	8.0	A
ESD per IEC 61000-4-2 (Air)	V <sub>ESD1</sub>	±30	kV
ESD per IEC 61000-4-2 (Contact)	V <sub>ESD2</sub>	±30	kV
Operating Temperature	T <sub>OPR</sub>	-55 to +150	
Storage Temperature	T <sub>STG</sub>	-55 to +150	

## / Electrical Characteristics(Ta=25 )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V <sub>RWM</sub>				24	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> =1mA	26.7			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =24V T=25			1	A
Clamping Voltage	V <sub>C</sub>	I <sub>PP</sub> =1.0A t <sub>p</sub> =8/20 S			33	V
	V <sub>C</sub>	I <sub>PP</sub> =8.0A t <sub>p</sub> =8/20 S			44	V
Capacitance. Any I/O pin to GND	C <sub>J</sub>	V <sub>R</sub> =0V f=1MHz		25	30	pF

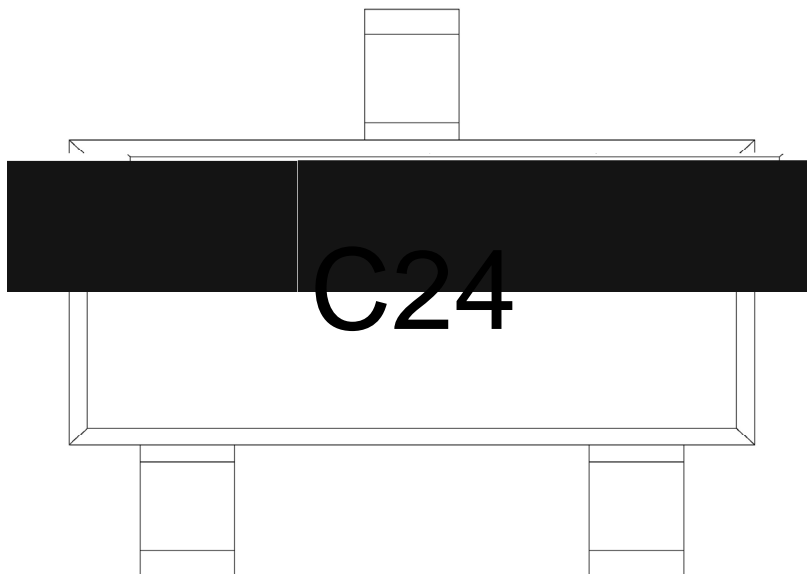
/ Electrical Characteristic Curve

**Fig.1 Non-Repetitive Pulse Po2.H03(e2.2r ve2.2s)-1.(. PulseT)18.(i)32.2me**





**/ Marking Instructions**



C24

Note:

C24: Product Type Code

**( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


**Note:**

- 1            150 200            60 120sec;    1.Preheating:150~200 , Time:60~120sec.
- 2            255±5                    5±0.5sec;    2.Peak Temp.:255±5 , Duration:5±0.5sec.
- 3                            2 10 /sec.            3.Cooling Speed: 2~10 /sec.

**/ Resistance to Soldering Heat Test Conditions**

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec
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